

Data sheet acquired from Harris Semiconductor SCHS035

CD4030B Types

CMOS Quad Exclusive-OR Gate

High-Voltage Types (20-Volt Rating)

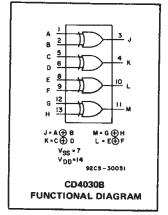
■ CD4030B types consist of four independent Exclusive-OR gates. The CD4030B provides the system designer with a means for direct implementation of the Exclusive-OR function.

The CD4030B types are supplied in 14-lead hermetic dual-in-line ceramic packages (D and F suffixes), 14-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).

Features:

- Medium-speed operation—tpHL, tpLH = 65 ns (typ.) at V_{DD} = 10 V, C_L = 50 pF
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V. 10-V. and 15-V parametric ratings
- Maximum input current of 1 µA at 18 V over full packagetemperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature

■ Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- Even and odd-parity generators and checkers
- Logical comparators
- Adders/subtractors
- General logic functions

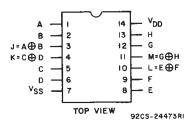
MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (VDD)

Voltages referenced to VSS Terminal)-0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS-0.5V to VDD +0.5V DC INPUT CURRENT, ANY ONE INPUT ±10mA POWER DISSIPATION PER PACKAGE (PD): For T_A = +100°C to +125°C...... Derate Linearity at 12mW/°C to 200mW DEVICE DISSIPATION PER OUTPUT TRANSISTOR

OPERATING-TEMPERATURE RANGE (TA).....-55°C to +125°C STORAGE TEMPERATURE RANGE (Tstg).....-65°C to +150°C LEAD TEMPERATURE (DURING SOLDERING):

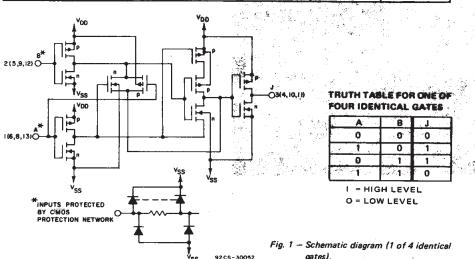
TERMINAL DIAGRAM Top View



RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS	ITS	
	MIN.	MAX.	UNITS
Supply-Voltage Range (For T _A = Full Package) Temperature Range)	3	18	į V



CD4030B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARAC-	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						2 Z C			
TERISTIC	v _o	VIN	VDD					+25		-	т		
	(V)	(V)	(V)	-55	–40	+85	+125	Min.	Тур.	Max.	s		
Quiescent Device Current, I _{DD} Max.		0,5	5	0.25	0.25	7.5	7.5		0.01	0.25	μΑ		
	_	0,10	10	0.5	0.5	15	15	-	0.01	0.5			
		0,15	15	1	1	30	30	·	0.01	1			
	-	0,20	20	5	5	150	150	_	0.02	5			
Output Low (Sink) Current IOL Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_			
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_			
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-			
Output High (Source) Current, IOH Min.	4.6	0,5	5	-0.64	-0.61	0.42	-0.36	-0.51	-1	_	m		
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_	ŀ		
	9.5	0,10	10	-1.6	1.5	-1.1	-0.9	-1.3	-2.6		1		
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8		1		
Output Voltage:		0,5	5		0	.05		_	0	0.05			
Low-Level,		0,10	10	0.05			_		0.05]			
VOL Max.	-	0,15	15	0.05			_	0	0.05	$]_{v}$			
Output Voltage:	_	0,5	5		4	.95		4.95	5		1		
High-Level,	_	0,10	10	9.95			9.95	10	_				
V _{OH} Min.	_	0,15	15	14.95			14.95	15	_	L			
Input Low Voltage, VIL Max.	0.5,4.5	-	5	1.5				_	1.5				
	1,9	1	10	3				-	-		3		
	1.5,13.5	-	15	4			_	-	4	l _v			
Input High Voltage, V _{IH} Min.	0.5,4.5	_	5			3.5		3.5	_	_			
	1,9	_	10			7	it.	. 7		_			
	1.5,13.5	-	15			11		11	-				
Input Current I _{IN} Max.	-	0,18	18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μ		

DYNAMIC ELECTRICAL CHARACTERISTICS at T $_A$ = 25°C; Input t $_r$, t $_f$ = 20 ns, C $_L$ = 50 pF, R $_L$ = 200 K Ω

CHARACTERISTIC		CONDITIONS				
		V _{DD}	LIMITS		UNITS	
		(V)	Тур.	Max.]	
Propagation Delay Time,	^t PLH, ^t PHL	5	140	280		
		10	65	130	ns	
		15	50	100		
Transition Time,		5	100	200		
	tTHL, tTLH	10	50	100	ns	
		15	40	80		
Input Capacitance,	CIN	Any Input	5	7.5	ρF	

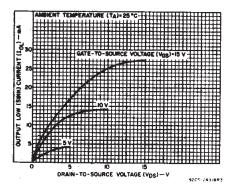


Fig. 2 — Typical output low (sink) current characteristics.

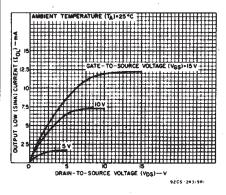


Fig. 3 – Minimum output low (sink) current characteristics.

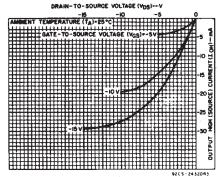


Fig. 4 — Typical output high (source) current characteristics.

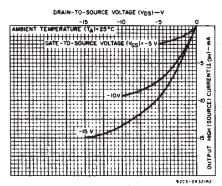


Fig. 5 – Minimum output high (source) current characteristics.

CD4030B Types

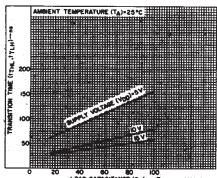


Fig. 6 — Typical transition time as a function of load capacitance.

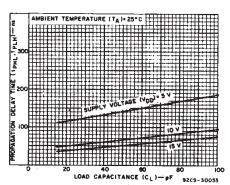


Fig. 7 — Typical propagation delay time as a function of load capacitance.

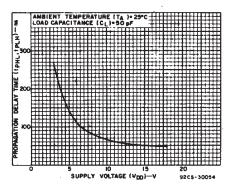


Fig. 8 — Typical propagation delay time as a function of supply voltage.

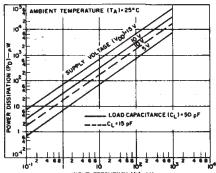


Fig. 9 — Typical dynamic power dissipation as a function of input frequency.

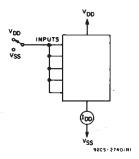


Fig. 10 - Quiescent-device current test circuit.

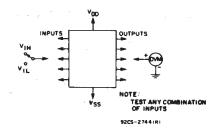


Fig. 11 — Input-voltage test circuit.

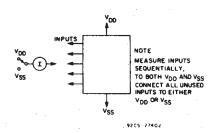


Fig. 12 - Input-current test circuit.

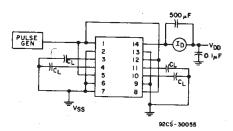
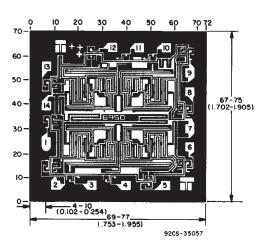


Fig. 13 – Dynamic power dissipation test circuit.



Dimensions and pad layout for CD4030BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

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